

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-10 (Canceled)

Claim 11 (Currently Amended)

A substrate treating apparatus for performing a predetermined treatment of substrates, comprising:

- a treating tank for immersing the substrates in a treating liquid stored therein;
- a holding arm for holding the substrates in vertical posture, said holding arm being movable to a treating position in said treating tank for immersing the substrates in the treating liquid;

- a storage device which stores a relationship between use history and treating rate of the treating liquid and an up-to-date use history of the treating liquid;

- a calculating device which derives a current treating rate R_m from said relationship between use history and treating rate of the treating liquid and said up-to-date use history of the treating liquid; and

- a computing device which ~~determines~~ derives a corrected treating time by extending a predetermined treating time according to said current treating rate A_1 from;

$$A_1 = T_i \bullet (R_i/R_m)$$

where T_i is a treating time specified in a recipe with reference to a fresh portion of said treating liquid, and R_i is a treating rate of the fresh portion;

wherein said substrates are treated for said corrected treating time A_1 .

Claim 12 (Previously Presented)

A apparatus as defined in claim 11, wherein said calculating device is arranged to take into account at least one of a treated number of substrates, a treating rate, a treating time, a substrate type, a rate of over-treatment, a substrate coverage of film and an initial treating rate.

Claim 13 (Previously Presented)

A apparatus as defined in claim 11, wherein said calculating device is arranged to take into account at least one of a treated number of substrates, a treating time and a substrate coverage of film.

Claim 14 (Currently Amended)

A apparatus as defined in claim 11, wherein said calculating treating time is an etching time and said treating rate is an etching rate, and said computing device is arranged to derive said corrected treating time from;

$$A1 = Ti \bullet (Ri/Rm)$$

where Ti is an etching time specified in a recipe with reference to a fresh portion of said treating liquid, Ri is an etching rate of the fresh portion, and Rm is the current etching rate.

Claims 15-16 (Canceled)**Claim 17 (Original)**

A apparatus as defined in claim 11, wherein said treating liquid includes phosphoric acid.

Claim 18 (Original)

A apparatus as defined in claim 12, wherein said treating liquid includes phosphoric acid.

Claim 19 (Original)

A apparatus as defined in claim 14, wherein said treating liquid includes phosphoric acid.